

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
14 April 2005 (14.04.2005)

PCT

(10) International Publication Number
WO 2005/033352 A2

(51) International Patent Classification⁷: **C23C**

(21) International Application Number:
PCT/US2004/022143

(22) International Filing Date: 9 July 2004 (09.07.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/485,912 9 July 2003 (09.07.2003) US

(71) Applicant (for all designated States except US): **FRY'S METALS INC.** [US/US]; 600 Route 440, Jersey City, NJ 07304 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **LEWIS, Brian, G.** [GB/US]; c/o Fry's Metals, Inc., 600 Route 440, Jersey City, NJ 07304 (US). **SINGH, Bawa** [US/US]; c/o Fry's Metals Inc., 600 Route 440, Jersey City, NJ 07304 (US). **DETIG, Robert, H.** [US/US]; 185 Union Avenue, New Providence, NJ 07974 (US). **MINOGUE, Gerard** [US/US]; 18700 Yorba Linda Blvd., #90, Yorba Linda, CA 92886 (US). **EBERLEIN, Dietmar, C.** [US/US]; 185 Union Avenue, New Providence, NJ 07974 (US).

REILLY, Kenneth [US/US]; c/o Fry's Metals Inc., 660 Route 440, Jersey City, NJ 07304 (US). **MARCZI, Michael** [US/US]; c/o Fry's Metals, Inc., 660 Route 440, Jersey City, NJ 07304 (US).

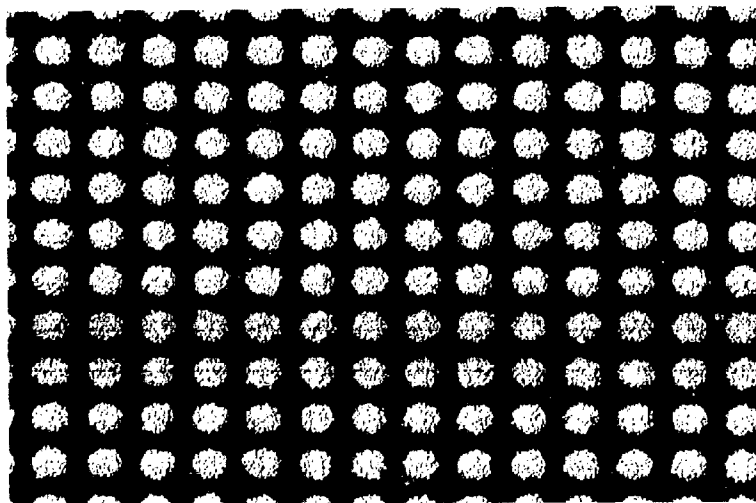
(74) Agents: **FLEISCHUT, Paul, I.J.** et al.; Senniger Powers, 1 Metropolitan Square, 16th Floor, St. Louis, MO 63102 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

[Continued on next page]

(54) Title: DEPOSITION AND PATTERNING PROCESS



(57) Abstract: A method for applying particles in a pattern to a substrate, either directly or by use of an intermediate tool, by electrokinetic or electrostatic means. A method for applying metal particles such as solder metal in a pattern to an electronic device substrate, either directly or by use of an intermediate tool, by electrokinetic or electrostatic means.

WO 2005/033352 A2



Published:

— without international search report and to be republished
upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.